V1 — 06/26

One-Step LEAD FREE No-Clean Desoldering Braid

SKU: 301-8 | Sizes: Type A 0.635mm x 10ft, Type B 1.27mm x 10ft, Type C 1.9mm x 5ft, Type C 1.9mm x 10ft, Type C 1.9mm x 25ft, Type D 2.54mm x 10ft, Type D 2.54mm x 25ft, Type E 3.175mm x 5ft

Features & Benefits

- **Lead-Free & No-Clean:** Ideal for use in lead-free soldering processes, with flux residue that doesn’t need cleaning.
- **High SIR Performance:** Conforms to Bellcore specification GR-78-CORE and IPC Test Method III, ensuring excellent insulation resistance.
- **Oxide-Free Copper:** Ensures clean, efficient desoldering without oxidation.
- **Static-Dissipative Spools:** Compliant with Mil. Standard 2000 and DOD Standard 1686 to prevent electrostatic discharge (ESD) damage.
- **More Copper Strands:** Offers more surface area per square inch, improving the braid’s solder absorption capacity.
- **Environmentally Friendly Manufacturing:** Made using the latest eco-friendly chemicals and processes under SPC guidelines.
- **Available in Various Lengths:** Choose from 5ft, 10ft, or 25ft reels to suit your needs.

About the One-Step LEAD FREE No-Clean Desoldering Braid

The One-Step LEAD FREE No-Clean Desoldering Braid is a premium, high-performance tool designed for efficient solder removal in electronics assembly and repair.
Ideal for use with RMA-type no-clean fluxes, this desoldering braid conforms to ANSI/J-STD-004, Type LO, and Bellcore specification GR-78-CORE, ensuring high SIR (Surface Insulation Resistance) performance. Made from oxide-free, clean copper and featuring more strands per square inch, this braid offers enhanced surface area for faster and more effective solder absorption. The flux residue left on the board does not need to be cleaned, making it perfect for quick and clean desoldering operations.

Specifications

Property	Detail
Application	ESD-protected areas, electronics mfg, cleanrooms